

CLAIMS

What is claimed is:

- 1 1. A land grid array on a carrier, the land grid array having a plurality of
- 2 electrical interconnections extending above the plane of the carrier,
- 3 comprising:
- 4 (a) a sash surrounding the perimeter of the land grid array.

- 1 2. A land grid array, as in claim 1, wherein the height of the sash is substantially
2 the same height as the electrical connections extending above the land grid
3 array.
- 1 3. A land grid array, as in claim 2, wherein the sash further comprises a noble or
2 semi-noble surface finish plating.
- 1 4. A land grid array, as in claim 3, wherein the noble or semi-noble surface finish
2 plating is made from a pure metal or an alloy from the group consisting of:
3 nickel, gold, palladium.
- 1 5. A land grid array, as in claim 1, wherein the sash is conductive and is of the
2 same material as the plurality of electrical interconnections.
- 1 6. A land grid array, as in claim 1, wherein the conductive sash is electrically
2 connected to a logic ground voltage.
- 1 7. A land grid array, as in claim 1, wherein the sash is a voltage path for any of a
2 plurality of other components on the carrier.
- 1 8. A land grid array, as in claim 7, wherein the voltage path is connected to a
2 secondary voltage other than a voltage of the electrical interconnections of the
3 land grid array.
- 1 9. A land grid array, as in claim 1, wherein the outer perimeter of the conductive
2 sash is slightly larger than the outer periphery of a frame of an electrical
3 interposer connector to be aligned onto the land grid array.

- 1 10. A land grid array, as in claim 9, further comprising at least one interior sash
2 surrounding each of a plurality of electrical interconnections, the enclosed
3 electrical interconnections being specific to one of a plurality of individual
4 chip domains residing on the multichip module.

- 1 11. A land grid array, as in claim 1, having a plurality of electrical connections
2 connecting the sash to selected ones of the plurality of electrical
3 interconnections.

- 1 12. A land grid array, as in claim 1, wherein the sash is manufactured
2 simultaneously with the manufacture of the plurality of electrical
3 interconnections.

- 1 13. A land grid array on a carrier, comprising:
2 (a) a plurality of electrical interconnections arranged into an array;
3 (b) a electrically conductive sash surrounding the perimeter of the array,
4 the sash having a width defined by an inner edge closest to the array
5 and an outer edge, the width of the sash larger than a frame having a
6 connector to be positioned onto the array, the sash having a height
7 substantially the same height as the plurality of electrical
8 interconnections extending above the plane of the carrier; and
9 (c) a plurality of electrical connections between the sash and array at
10 selected electrical interconnections.

- 1 14. A carrier with a land grid array for use with a land grid array interposer
2 connector, the land grid array having of multitude of electrical
3 interconnections, comprising:
- 4 (a) placement means for the land grid array interposer to rest upon when
5 placed on top of the land grid array for electrical connection;
- 6 (b) means to provide a more uniform height and surface finish of the
7 electrical interconnections spanning interior regions of an area toward
8 an outer periphery of the array where the interposer is placed upon the
9 placement means; and
- 10 (c) means to prevent particulate and gaseous contamination of the array of
11 electrical interconnections when an interposer is placed onto the array.
- 1 15. The carrier of claim 14, wherein said placement means, said uniform height
2 means, and said prevention means is an electrically conductive sash
3 surrounding the periphery of the land grid array.